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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10026454	FILING DATE 12/27/2001	CLASS 257	SUBCLASS -	GAU 2811	EXAMINER W. Williams
**APPLICANTS: Takeuchi Hiroki; Kojima Toshifumi; Ohbayashi Kazushige; Kashima Masahito;					
**CONTINUING DATA VERIFIED:					
NOTE-DISCLAIMER: The term of this patent shall not extend beyond the expiration date of Pct. No. 6,284,837					
** FOREIGN APPLICATIONS VERIFIED: JAPAN P.2000-401931 12/28/2000 JAPAN P.2001-255781 08/27/2001					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>			RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiner's initials			ATTORNEY DOCKET NO Q67930		
TITLE : Embedding resin and wiring substrate using the same					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg.
Primary Examiner		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
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ISSUE FEE	
Amount Due	Date Paid

☒ **TERMINAL
DISCLAIMER**

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